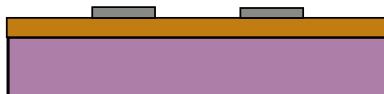
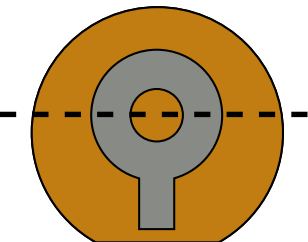


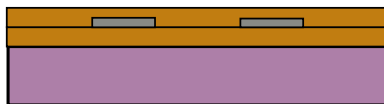
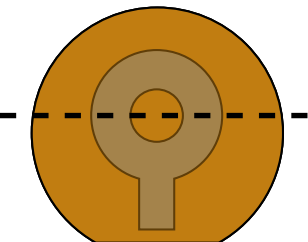
substrate (polyimide 5 μm)

spincoating



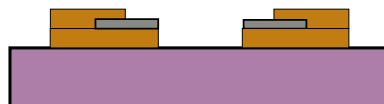
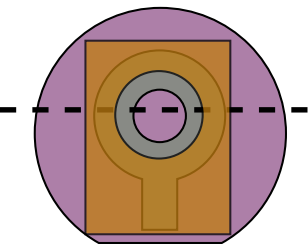
conductors (platinum 100 nm)

evaporation + liftoff



insulation (polyimide 5 μm)

spincoating



via opening, singulation

Reactive Ion Etching